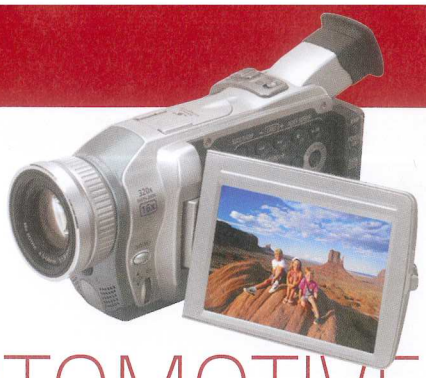
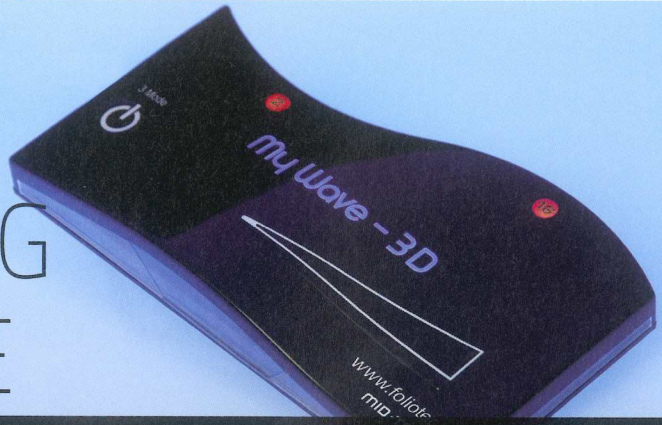


FOR DISPLAYS, ELECTRONICS AND AUTOMOTIVE

Expanded portfolio of PC film grades Sabic Innovative Plastics has announced the expansion of its Lexan PC (polycarbonate) portfolio with the launch of three additional film grades. Lexan HP92TTY coated film for 2.5 dimensional formed parts offers chemical and abrasion resistance, can be embossed and requires no post-curing. Lexan 6060 film for IMD overlays on three-dimensional parts is printable and offers high gloss, light transmission and increased surface hardness. Lexan OQ8DA dual-coated sheeted film is designed to provide good impact performance and is printable.

www.sabic-ip.com

[...] Read more online about PC film grades. (670 words) **Article code: S3R**



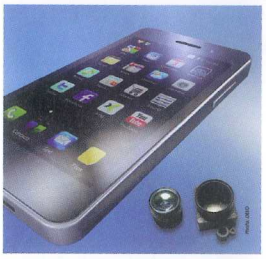
FOLLOWING THE CURVE

Capacitive sensors in 3D Kunststoff Helmbrechts' and MID-Tronic's novel MyWave touch-sensitive components use a newly-developed circuit board technology to offer systems that break out of flat surface shapes. The MyWave-Demonstrator features surface curvature of 18mm. The 3D's PCB follows the curved shape of a front part decorated by in mould labelling (IML). It acquires its capacitive surface and other features through laser direct structuring (LDS) and is populated by a six-axis robot and highly-accurate automatic SMT placement unit which has the capacity to act at deformation heights of up to 5cm.

www.helmbrechts.de

[...] Read more online about capacitive 3D sensors. (720 words) **Article code: QE9**

MAKE IT MINI



Solutions for microelectronics The trend towards miniaturisation in relation to electronic equipment can only be achieved with the corresponding materials, technologies and bonding processes. Thus, for example, mobile phone cameras are bonded on a printed circuit board which is then soldered with other surface-mounted device (SMD) components in the reflow oven. This soldering process, in which peak temperatures of 260°C are reached, requires high resistance on the part of plastic components and adhesives. Delo, manufacturer of industrial adhesives, has developed an adhesive solution that allows the liquid crystal polymer (LCP) Vectra from Ticona to adhere to the composite material FR4 and ceramic boards even after a triple reflow process.

www.delo.de ■ www.ticona.com

[...] Read more online about microelectronic solutions. (580 words) **Article code: B7H**